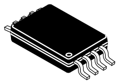
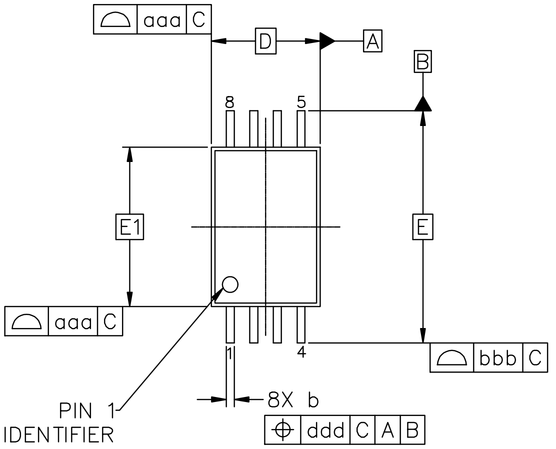
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS



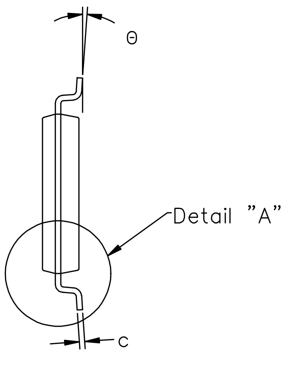
SCALE 2:1

TSSOP−8 3.00x4.00x0.90, 0.65P
CASE 948S
ISSUE D

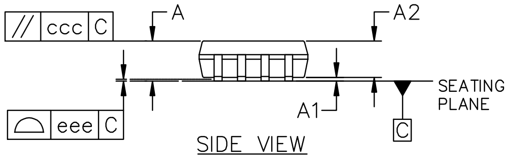
DATE 24 OCT 2025



TOP VIEW

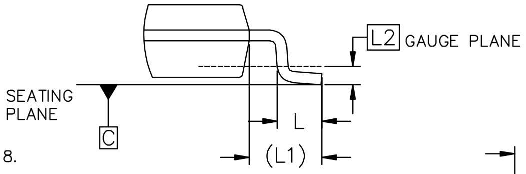


FRONT VIEW



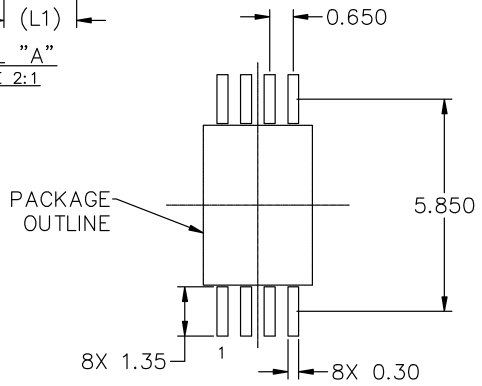
SIDE VIEW

DIM	MILLIMETERS MIN	MILLIMETERS NOM	MILLIMETERS MAX
A	0.90	1.00	1.10
A1	0.05	0.10	0.15
A2	0.80	0.90	1.00
b	0.19	0.25	0.30
c	0.09	0.15	0.20
D	3.00 BSC		
E	6.40 BSC		
E1	4.40 BSC		
L	0.50	0.60	0.70
L1	1.00 REF		
L2	0.25 BSC		
θ	0°	4°	8°
TOLERANCE FORM & POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.10		
eee	0.05		



DETAIL "A"
SCALE 2:1

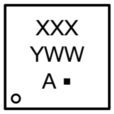
NOTES:
1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
4. DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
5. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07mm.



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb−Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	**TSSOP−8 3.00x4.00x0.90, 0.65P**	**PAGE 1 OF 1**